

## Electronic Acknowledgement Receipt

<b>EFS ID:</b>	9289642
<b>Application Number:</b>	10055560
<b>International Application Number:</b>	
<b>Confirmation Number:</b>	6103
<b>Title of Invention:</b>	INTEGRATED CHIP PACKAGE STRUCTURE USING METAL SUBSTRATE AND METHOD OF MANUFACTURING THE SAME
<b>First Named Inventor/Applicant Name:</b>	Mou-Shiung Lin
<b>Customer Number:</b>	89518
<b>Filer:</b>	Dennis Alan Duchene/Patricia Balero
<b>Filer Authorized By:</b>	Dennis Alan Duchene
<b>Attorney Docket Number:</b>	085027-0058
<b>Receipt Date:</b>	24-JAN-2011
<b>Filing Date:</b>	22-JAN-2002
<b>Time Stamp:</b>	13:59:20
<b>Application Type:</b>	Utility under 35 USC 111(a)

### Payment information:

Submitted with Payment	no
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### File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/Message Digest	Multi Part/.zip	Pages (if appl.)
1	DolceralInformationDisclosureStatement-085027-0058.pdf		166992 8d98a864570215e0ff1d2b61d453c251fb 8sec	yes	5

Multipart Description/PDF files in .zip description					
	Document Description		Start	End	
	Transmittal Letter		1	3	
	Information Disclosure Statement (IDS) Filed (SB/08)		4	5	

**Warnings:**
**Information:**

2	Foreign Reference	TW385509_FRN00123.pdf	6828863 d5ca02e3a2145d4dd0e163131f9fc21231d9eb8	no	53
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**Warnings:**
**Information:**

3	Foreign Reference	TW417265_FRN00124.pdf	2756476 21b2d108961c7c71782a78d0f9ccac111 6325a	no	26
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**Warnings:**
**Information:**

4	Foreign Reference	TW449894_FRN00122.pdf	2918238 912b22cf98695ed45d44753d45cd46939c 48263	no	28
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**Warnings:**
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5		TK-42InformationDisclosureStatement-085027-0058.pdf	158601 210a85d1df92a352e0598762982a0d6a1ac 41da	yes	4
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**Multipart Description/PDF files in .zip description**

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	Transmittal Letter		1	2	
	Information Disclosure Statement (IDS) Filed (SB/08)		3	4	

**Warnings:**
**Information:**

6		TS-5InformationDisclosureStatement-085027-0058.pdf	159434 fe16e111370a8977235e666c3e08de341c6 d9fa	yes	4
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**Multipart Description/PDF files in .zip description**

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7		OrphanInformationDisclosureStatement-085027-0058.pdf	188724 7082fb674c7620f0d051a6c8ef5b06d14f1 bfc7	yes	5			
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8	NPL Documents	1_MISTRY_45nm_logic.pdf	2254221 672127b124142b63448b3638577e90a7f5 81092	no	4			
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9	NPL Documents	2_EDELSTEIN_Advantages_of_Copper.pdf	3696109 d4a21264b1bf4d203a70ba29e619c946550 68f74	no	9			
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10	NPL Documents	3_THENG_An_automated_tool_deployment_for_ESD.pdf	4517666 1a360bd7c7b154720da4bc4129a92c81a aefb74	no	7			
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11	NPL Documents	4_GAO_An_improved_electrostatic_discharge_protection_structure.pdf	885848 7805c75db4f5367c0064f35e1853c2a0776 ab65	no	6			
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12	NPL Documents	5_YOEH_Copper_Die_Bumps.pdf	717153 6ea9c2a4fc3f9c0d5e0d44c6c4bb4d31beec08a	no	5			
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13	NPL Documents	6_HU_Copper_Polymide.pdf	436455 60f008adcc448863be25d4d02121b1176e2 67a05	no	7			
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14	NPL Documents	7_ROESCH_Cycling_Copper_Flip_Chip_Connects.pdf	1142794 813203f7f462423e7e041a8f93ec24a5e1577ab57	no	8
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15	NPL Documents	8_LEE_Effect_of_ESD_layout_on_the_assembly_yield.pdf	889090 a726222581358d2992120de7b2102f59416614	no	4
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17	NPL Documents	10_EDELSTEIN_Full_copper_wiring.pdf	1205963 9501660bb654c309018e197ed026a/b2bc14322	no	4
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20	NPL Documents	13_GROVES_HighQ_Inductors_in_a_SiGe_BiCMOS_process.pdf	420788 8c362f6d6459f4cc0d415b5f5dc4a315999f6dc	no	4
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22	NPL Documents	15_KUMAR_Intel_ISSCC_2009_paper_on_power_on_chip.pdf	2528325 cd8aeb905c311c18-91a5d8f93d13938418	no	2
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31	NPL Documents	24_PDF_MALONEY_Stacked_P MOS_clamps_for_high_voltage _power_supply_protection_pd f_pdf.pdf	1327621 bf7254639d1899a52c02a1501456f1259e b6e88	no	8
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34	NPL Documents	27_PDF_LIN_Post_Passivation_Technology_Presentation_for_TSMC_Tech_Symposium_2003.pdf.pdf	1277639 2055fe2754a2807cc28bcc5d8f924f52711e99	no	32
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35	NPL Documents	28_PDF_LIN_A_New_IC_Connection_Scheme_and_Design.pdf.pdf	116206 e1e1dabb5cd000720de6779f0a0e7106cecb8	no	4
<b>Warnings:</b>					
<b>Information:</b>					
<b>Total Files Size (in bytes):</b>					53953303
<p><b>This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.</b></p> <p><b>New Applications Under 35 U.S.C. 111</b>            If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.</p> <p><b>National Stage of an International Application under 35 U.S.C. 371</b>            If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.</p> <p><b>New International Application Filed with the USPTO as a Receiving Office</b>            If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.</p>					